

**AMENDMENTS TO THE SPECIFICATION:**

Please amend the specification as follows:

Applicants note a marked-up version and a clean copy of the substitute Specification is provided in the Attachments.

On page 11, please replace the "Abstract" with the following:

The invention relates to a miniaturised surface mount optoelectronic component. An electrically conductive material (1) preferably metal frame is used to serve as the base for the assembly. ~~Optionally the cavity (2) may be formed within this electrically conductive base material to serve as a reflector cup.~~ An optoelectronic chip [(3)] is mounted ~~within this cavity~~ on the base assembly. The whole base material is then encapsulated with a hard transparent or translucent resin material (4) ~~so~~ such that optical radiation may be transmitted or received via this medium. Electrical ~~connection(s)~~ connections between the chip and the base material ~~is~~ are provided by a ~~metallic wire or wires (6) wires.~~ Soldering terminals are part of the electrically conductive frame and are exposed at the bottom and side portions of the component. The soldering terminals do not extend beyond the outline of the encapsulation material.

~~The Most Illustrative Drawing: FIG. A~~